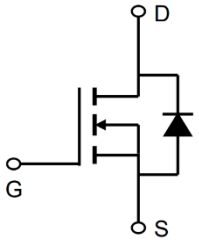
AP60N04DF

40V N-Channel Enhancement Mode MOSFET

Description

The AP60N04DF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



General Features

V_{DS} = 40V I_D =60 A

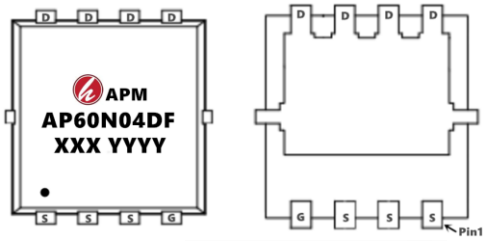
$R_{DS(ON)}$ < 15.5mΩ @ V_{GS}=10V

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP60N04DF	PDFN3*3-8L	AP60N04DF XXX YYYY	5000

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	60	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1]	26	A
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	10	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ 10V[1]	8	A
I_{DM}	Pulsed Drain Current[2]	100	A
EAS	Single Pulse Avalanche Energy[3]	31	mJ
I_{AS}	Avalanche Current	25	A
P_D@T_C=25℃	Total Power Dissipation[4]	34.7	W
P_D@T_A=25℃	Total Power Dissipation[4]	2	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State)[1]	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	3.6	℃/W

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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	40	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , I_D=1mA	---	0.034	---	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=20A	---	12.5	15.5	mΩ
		V_{GS}=4.5V , I_D=10A	---	14.5	20	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.0	1.5	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.64	---	mV/°C
I_{DSS}	Drain-Source Leakage Current	V_{DS}=32V , V_{GS}=0V , T_J=25°C	---	---	1	uA
		V_{DS}=32V , V_{GS}=0V , T_J=55°C	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=20A	---	36	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	2.1	4.2	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=20V , V_{GS}=4.5V , I_D=12A	---	10.7	---	nC
Q_{gs}	Gate-Source Charge		---	3.3	---	
Q_{gd}	Gate-Drain Charge		---	4.2	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=12V , V_{GS}=10V , R_G=3.3 I_D=6A	---	8.6	---	ns
T_r	Rise Time		---	3.4	---	
$T_{d(off)}$	Turn-Off Delay Time		---	25	---	
T_f	Fall Time		---	2.2	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	1314	---	pF
C_{oss}	Output Capacitance		---	120	---	
C_{rss}	Reverse Transfer Capacitance		---	88	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	42	A
I_{SM}	Pulsed Source Current[2,5]		---	---	100	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25°C	---	---	1.2	V

Note :
1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=25A
4.The power dissipation is limited by 150°C junction temperature
5 .The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

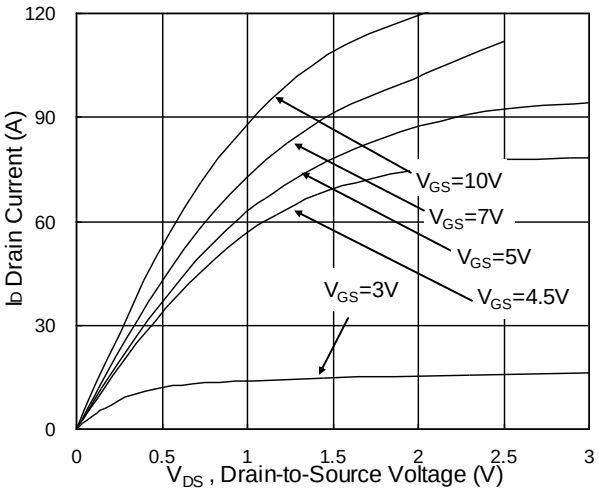

Fig.1 Typical Output Characteristics

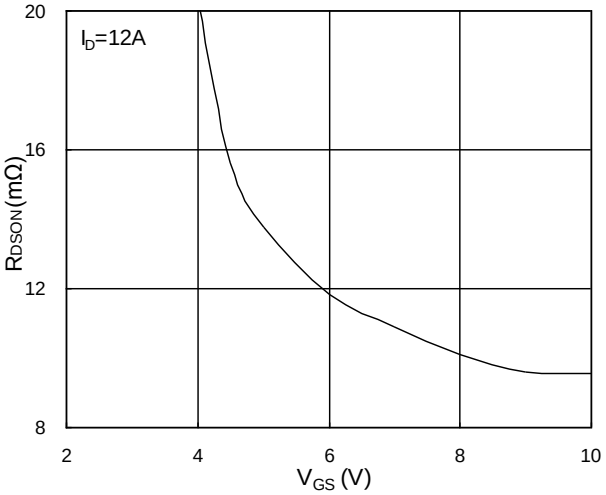

Fig.2 On-Resistance vs. G-S Voltage

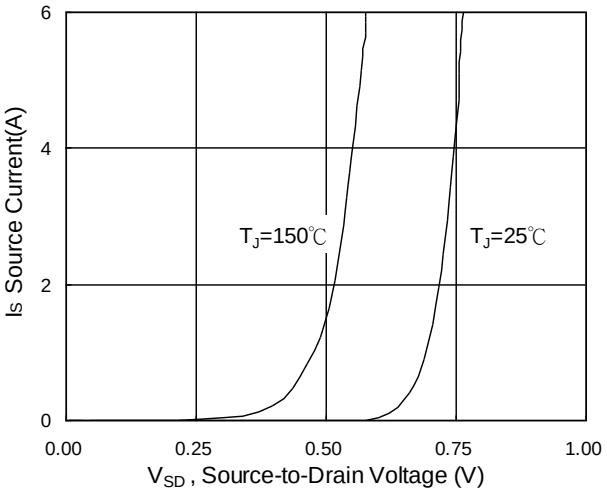

Fig.3 Forward Characteristics of Reverse

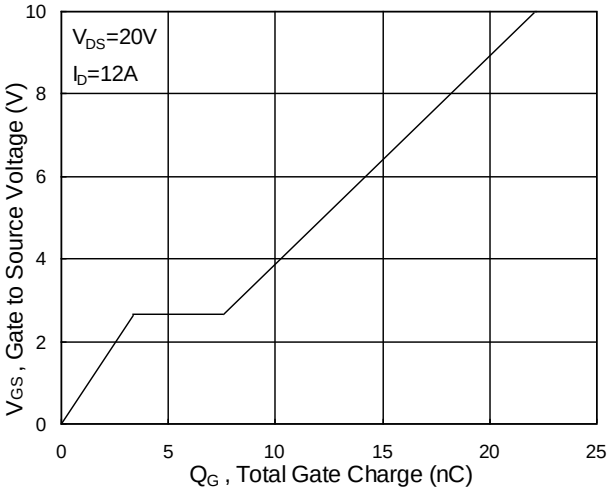

Fig.4 Gate-Charge Characteristics

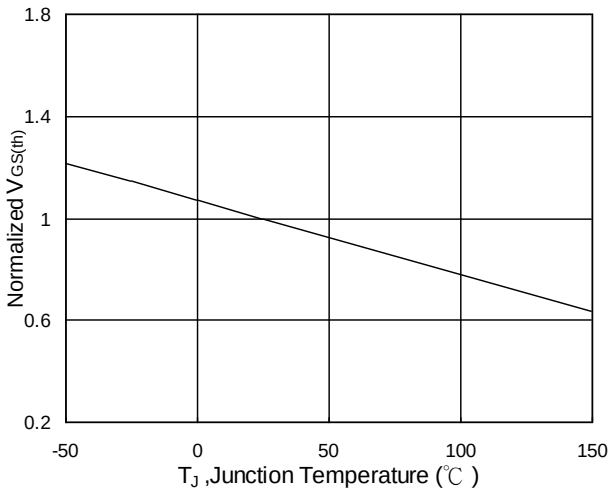

Fig.5 $V_{GS(th)}$ vs. T_J

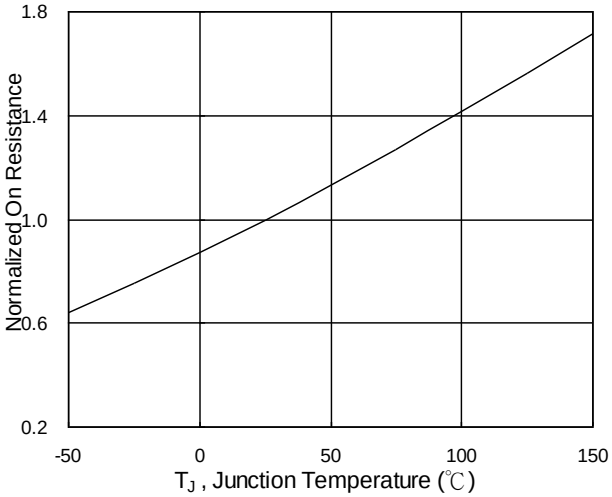

Fig.6 Normalized R_{DSON} vs. T_J

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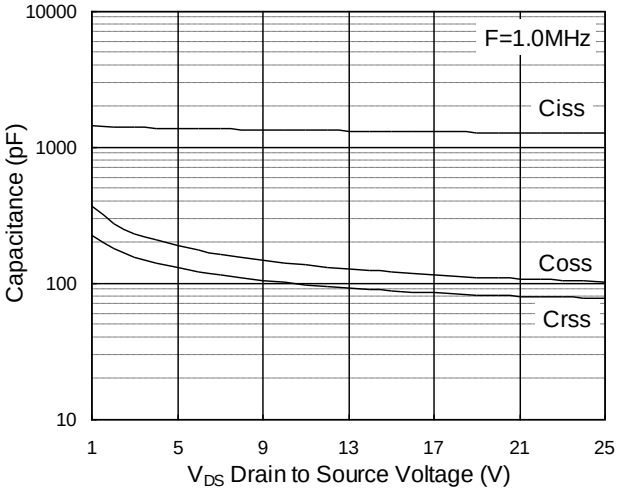

Fig.7 Capacitance

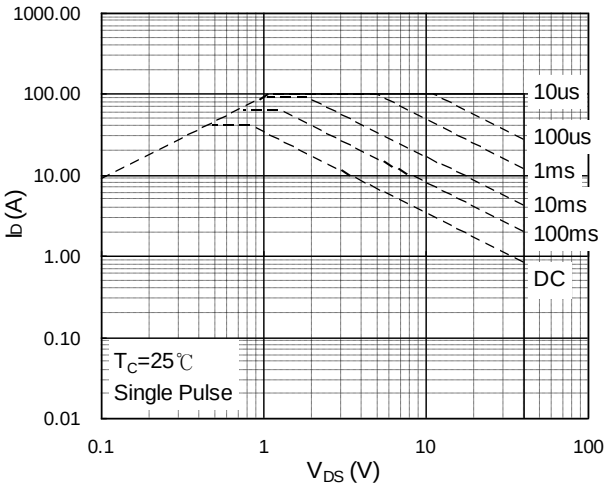

Fig.8 Safe Operating Area

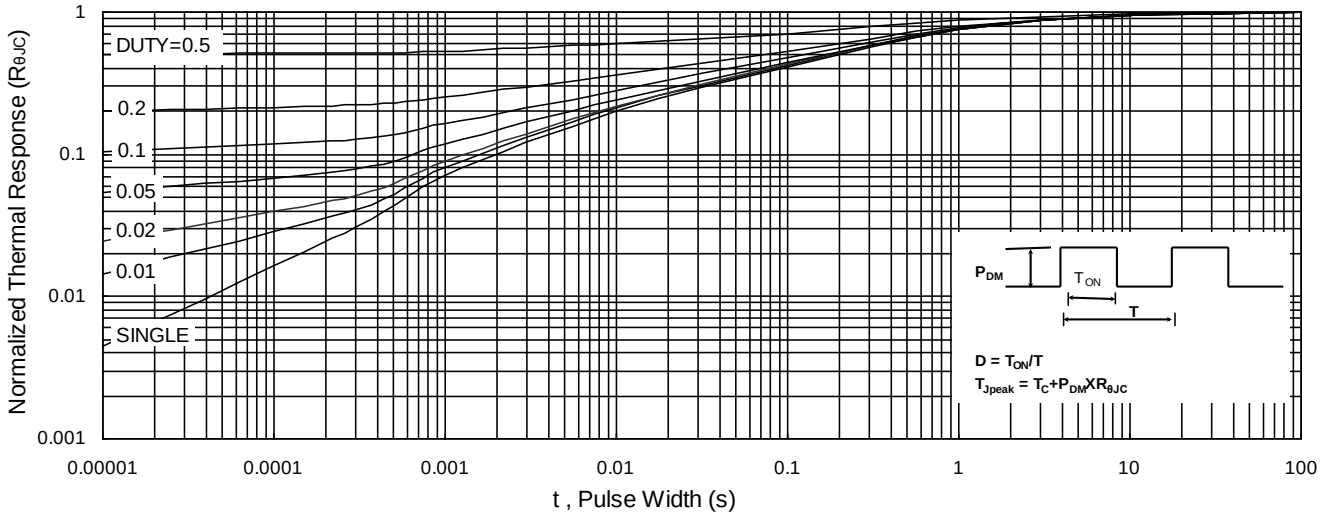

Fig.9 Normalized Maximum Transient Thermal Impedance

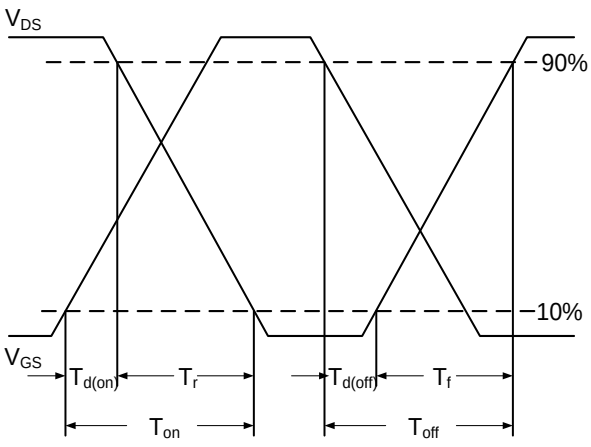

Fig.10 Switching Time Waveform

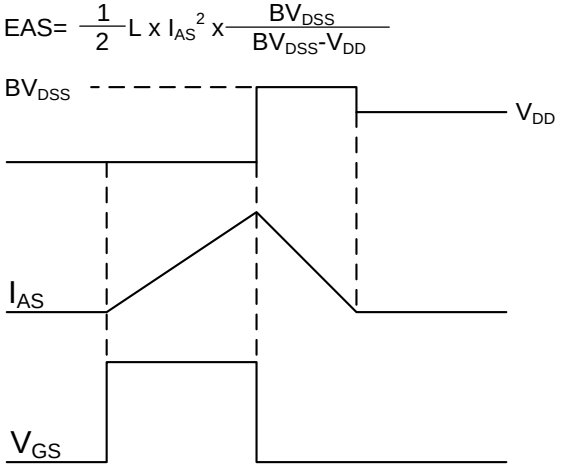

Fig.11 Unclamped Inductive Switching Waveform

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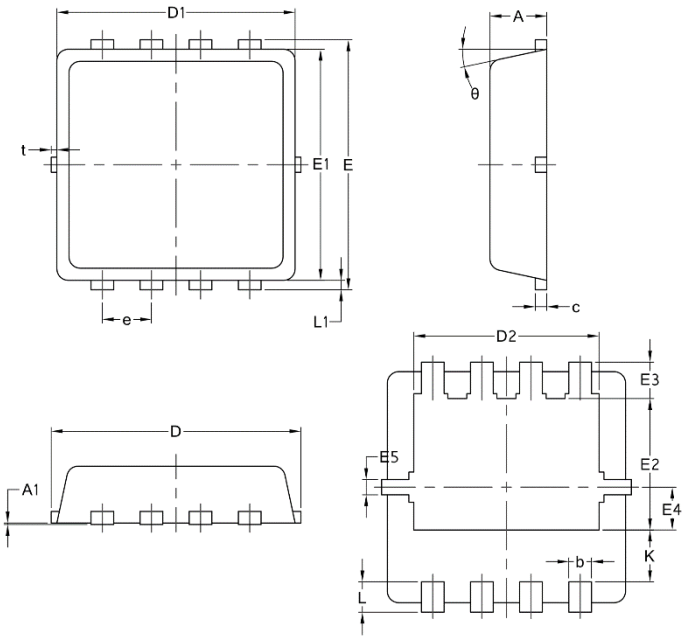
Package Mechanical Data-DFN3*3-8L-JQ Single



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14

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Edition	Date	Change
Rve1.0	2019/4/31	Initial release